REVISION DATE: 4/28/05 REVISION: A



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124-05 SPRAYABLE, B-STAGEABLE, SILVER PLATED COPPER FILLED, ELECTRICALLY CONDUCTIVE EPOXY COATING

DESCRIPTION: 124-05 is a sprayable, B-Stageable, silver plated copper filled, electrically conductive, one part epoxy coating. This product is designed for bonding capacitors to lead frames; other applications include, but are not limited to the assembling electrical and electronic components and EMI/RFI shielding. This system features excellent thermal stability.

PROPERTIES:

Viscosity (cps) 1000-1200

Filler Silver Plated Copper

 $\begin{array}{lll} \text{Percent Solids, cured} & > 68 \\ \text{Glass Trans. Temp. (°C)} & 100 \\ \text{Surface Resistivity, max. } (\Omega/\text{Sq/Mil}) & 0.075 \\ \text{Solderable} & \text{No} \\ \text{Hydrolytic Stability} & \text{Excellent} \\ \text{Useful Temperature Range (°C)} & -55 \text{ to } +230 \\ \text{Thermal Stability} & \text{Good to } 325 \\ \end{array}$

T-Shear Strength (psi) 2100

SUGGESTED HANDLING AND CURING: Material is ready to use as received. Store frozen to maintain consistent flow properties. Allow material to warm up to room temperature before opening container. Prior to using, be certain to resuspend silver plated copper. As an adhesive, apply 124-05 to one or both parts, then mate the parts and cure for one (1) hour at 150°C while maintaining pressure. 124-05 can be thinned further with small amounts of CMI# 113-39 (fast drying), #114-20 (slow drying) thinners.

STORAGE: Shelf Life -2 month at 25°C; or 6 months at -10°C.

B-STAGE PROCEDURE: Apply adhesive to substrate. Next apply heat to advance the curing to the non-tacky stage when cooled to room temperature. A temperature of 125°C for 1-2 minutes is required, B-Stage time is mass related. User is encouraged to experiment for optimum drying time at a given temperature. Store on release liner to prevent contamination.

STORAGE B-STAGED FILM: Shelf Life - 1 month @ 25°C; or 3 months @ -10°C

BONDING PROCEDURE: To use, carefully align parts to be bonded, apply uniform pressure to maintain location. Cure for 1 hour at 150°C. (Note cure times given are mass related, timing should start after adhesive and substrates reach curing temperature.)

SAFETY AND HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.